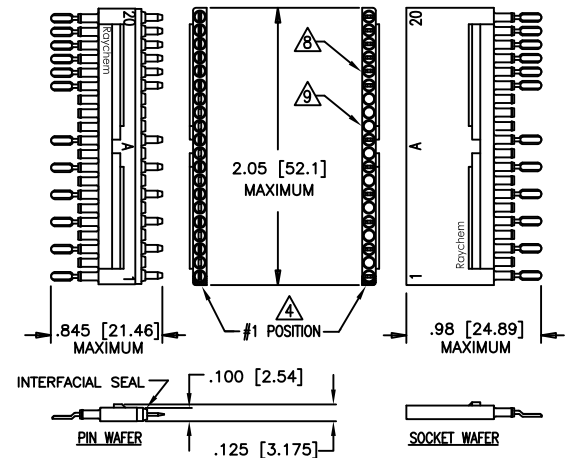
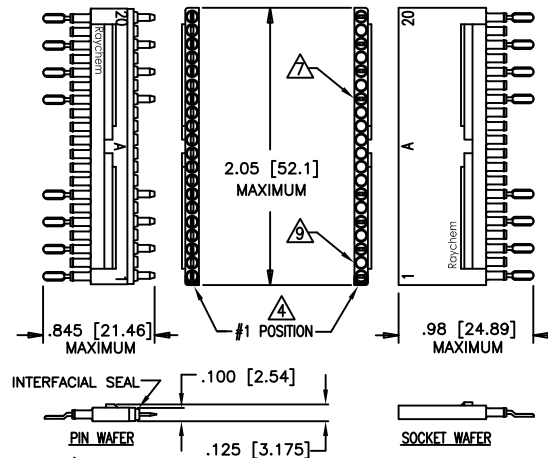
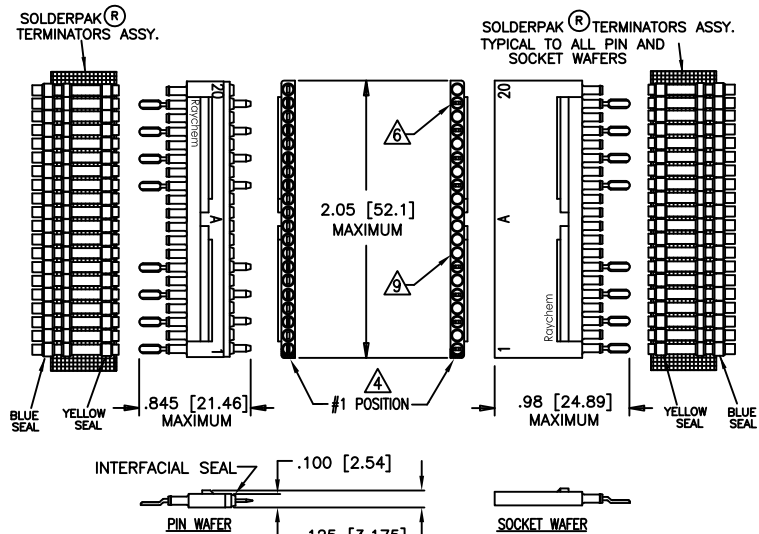


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REVISIONS			
LTR	DESCRIPTION	DATE	APPROVED
A	PER ECO-10-015431	JULY/27/2010	M. HIGGY
B	PER ECO-11-003194	Feb/14/2011	M. HIGGY
B1	PER ECO-11-004231, Administrative change	Feb/25/2011	M. HIGGY

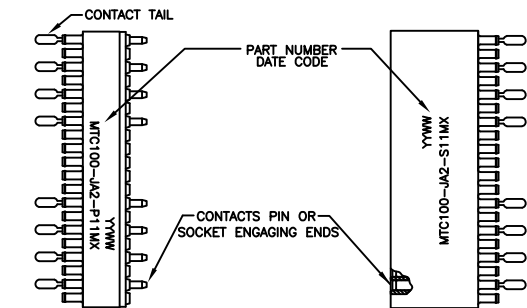


△ THIS MODEL HAS 8 ACTIVE CONNECTIONS, (VERSION 2)
 LINE 2, 4, 6, 8, 9, 10, 11, 12, 13, 15, 17
 AND 19 CONNECTIONS DO NOT EXIST.

△ THIS MODEL HAS 12 ACTIVE CONNECTIONS.
 LINE 2, 4, 6, 8, 10, 12, 13 AND 14
 CONNECTIONS DO NOT EXIST.

FIGURE II

FIGURE III



△ THIS MODEL HAS 8 ACTIVE CONNECTIONS, (VERSION 1)
 LINE 2, 4, 6, 8, 9, 10, 11, 12, 14, 16, 18
 AND 20 CONNECTIONS DO NOT EXIST.

FIGURE I

- NOTES:
- PART NUMBER VARIABLE: SEE TABLE I.
 - MATERIAL:
 - A) PIN/SOCKET WAFER HIGH GRADE POLYARYLENE THERMOPLASTIC.
 - B) PIN CONTACT COPPER ALLOY PER ASTM B36, ASTM B36M
 - C) SOCKET CONTACT COPPER ALLOY PER ASTM B103, ASTM B103M (A).
 - D) INTERFACIAL SEAL FLUOROSILICONE PER MIL-R-25988.
 - E) SOLDERPAK (R) TERMINATORS ASSY. REFER TO TYCO ELECTRONICS DRAWING CTA-0036.
 - FINISH:
 - A) PIN/SOCKET WAFER AS MOLDED.
 - B) PIN/SOCKET CONTACT ENGAGING END GOLD PLATE PER ASTM B488, CLASS 1, TYPE 2, GRADE C.
 - C) CONTACT TAIL SOLDER COATED PER IPC J-STD 006 (Sn63).
 - NUMBER ONE POSITION IS MARKED AS SHOWN IN CONTRASTING COLOR ON INTERFACE.
 - THIS PRODUCT IS QUALIFIED TO SPACE SYSTEM LORAL'S SPECIFICATION 010554 Rev. 21, (PER MIL-DTL-83513 AND TYCO ELECTRONICS SPECIFICATION C-6111 AS APPLICABLE). SEE ISTR-1105 FOR MORE INFORMATION.
 - SEE FIGURE I
 - SEE FIGURE II
 - SEE FIGURE III
 - ALL UNUSED CAVITIES ON SOCKET WAFERS ARE FOR VENTING (OPEN).

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FIGURE	TABLE I		
	PART#	DESCRIPTION	WEIGHT MAX. GRAMS
I	MTC100-JA2-P11M1	A WAFER, PIN △	T.D.
	MTC100-JA2-S11M1	A WAFER, SOCKET △	T.D.
II	MTC100-JA2-P11M2	A WAFER, PIN △	T.D.
	MTC100-JA2-S11M2	A WAFER, SOCKET △	T.D.
III	MTC100-JA2-P11M3	A WAFER, PIN △	T.D.
	MTC100-JA2-S11M3	A WAFER, SOCKET △	T.D.

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CUSTOMER DRAWING

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. METRIC DIMENSIONS ARE IN BRACKETS.	DRAWN	Zsofia O.	July/19/2010		Raychem Interconnect 300 Condit/Bon Drive Menlo Park, CA 94025 U.S.A.
	CHECKED				
DECIMALS .XXX ± .005 .XX ±	APPROVED			TITLE A WAFER 2 INCH, PIN AND SOCKET FOR ROUND WIRE TERMINATION 20-26 AWG 125 CELSIUS DEGREE OPERATING TEMPERATURE MTC100 SERIES-MODIFIED 3 VARIATION CONTACTS MODELS	SIZE A
	APPROVED	M.HIGGY.	July/19/2010		
ANGLES .X ±	CAD NAME	MTC100-JA2-X11MX		CAGE CODE: 06090	DWG. NO. MTC100-JA2-X11MX
WEIGHT: MAXIMUM SEE TABULATION	THIRD ANGLE PROJECTION			SCALE: NONE	REV B1

DRAWING MTC100-JA2-X11MX SHEET 1